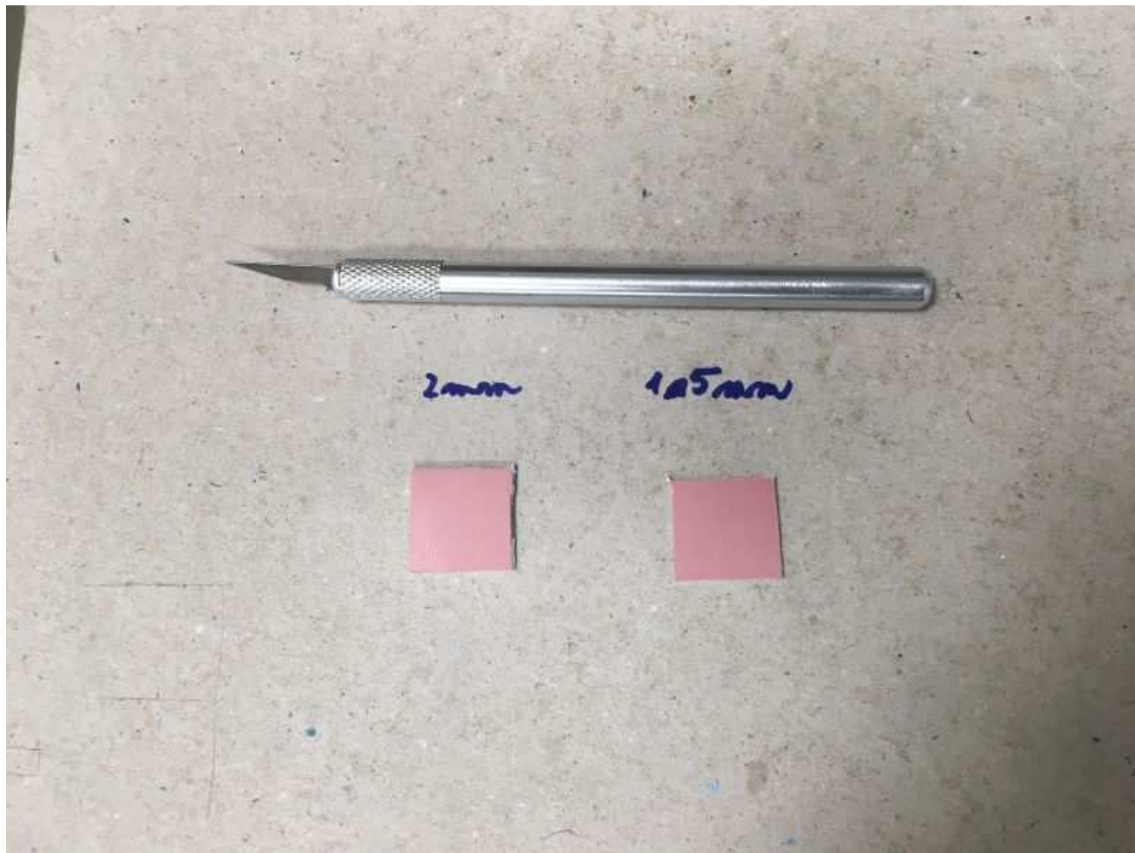


Brief step-by-step procedure for the thermal pad mounting into the GazeT LED module (STR-DMS-NCV7694-GEVB)

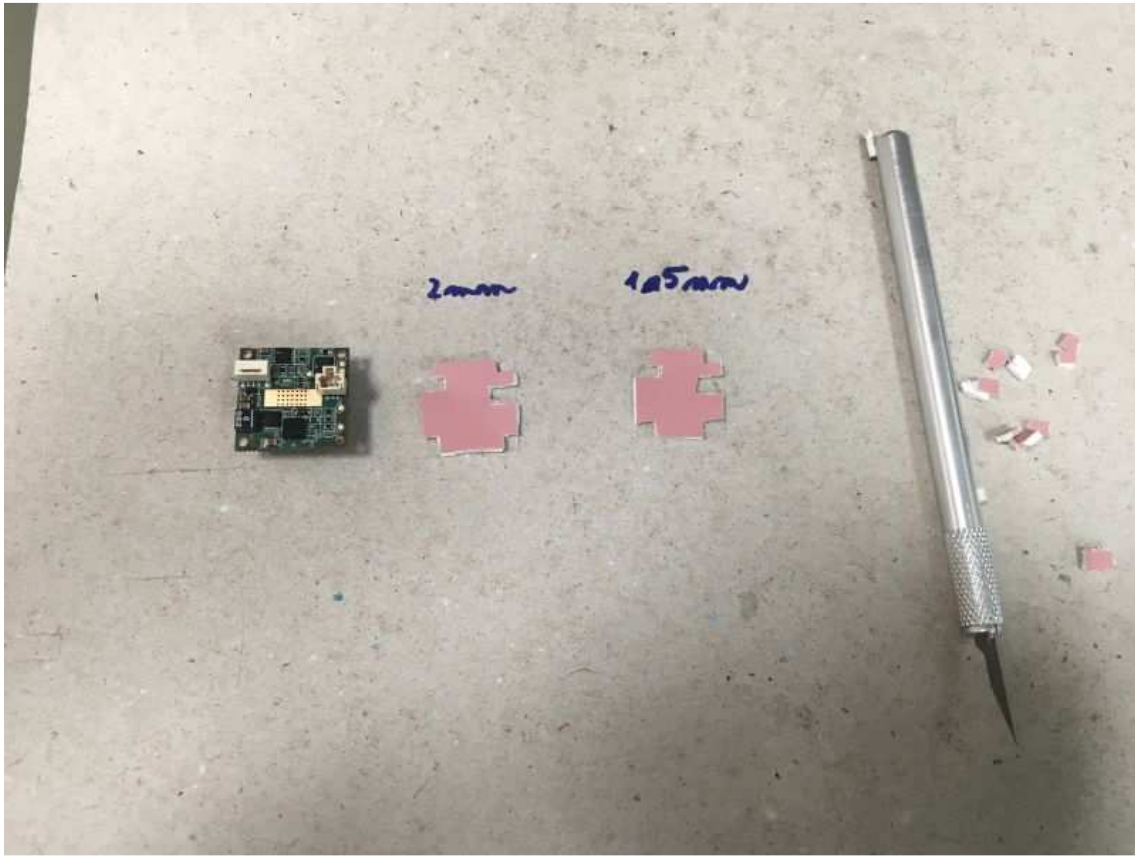
1. The [MPGCSP15USGF-200-2.0](#) (1pc) and the [MPGCSP15USGF-200-1.5](#) (1pc) thermal pads are used to create thermal pad sandwich to fill the space in the GazeT LED module and thereby ensure proper heat transfer from PCB to metal body.

Cut the thermal pads in shape square of dimension 19x19mm (or 18x18mm). Start cutting from the pink-colored side and in the next step rotate the thermal pad by 180degrees and finish the cut from the bottom side (transparent foil is placed at the bottom).



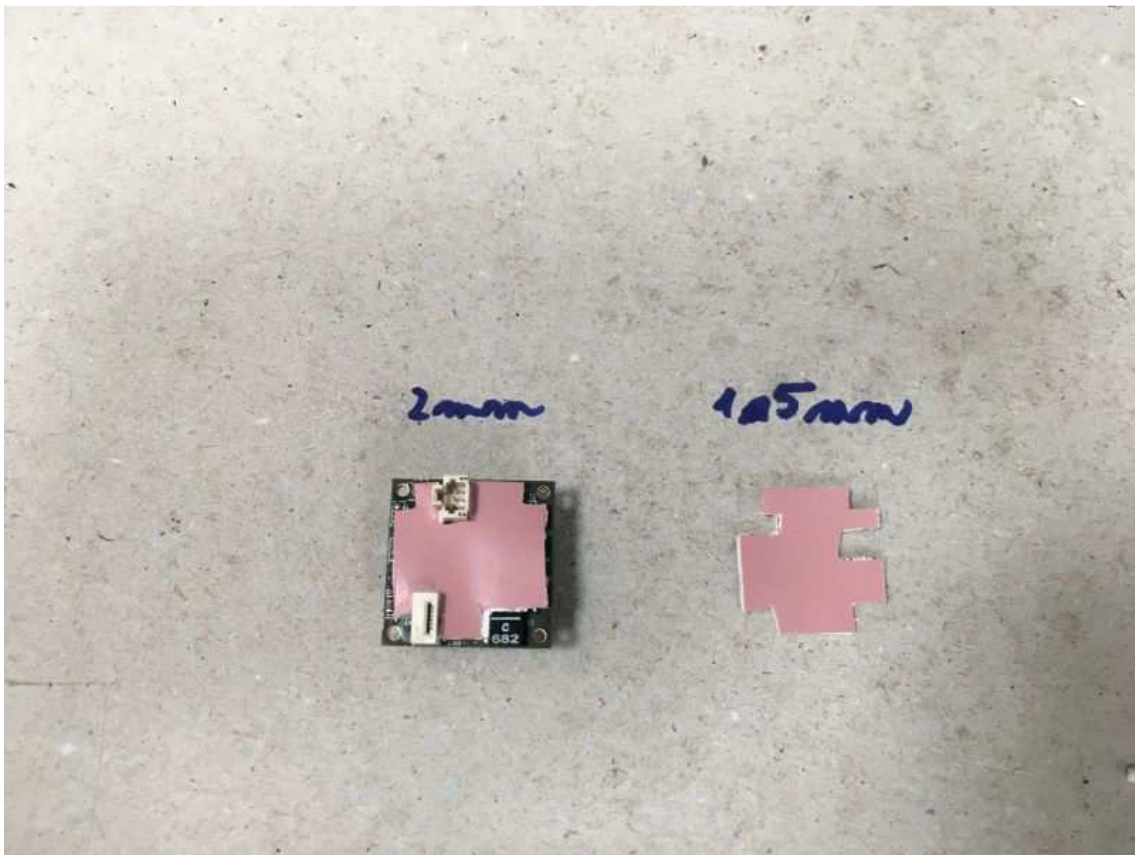
19x19mm thermal pad cuts

2. Prepare thermal pad cut-outs. A separate PDF ([thermal_pad_dimensions.pdf](#)) discusses dimensions for the thermal pad cut-outs. This PDF applies for both thermal pad materials (1.5mm and 2mm).

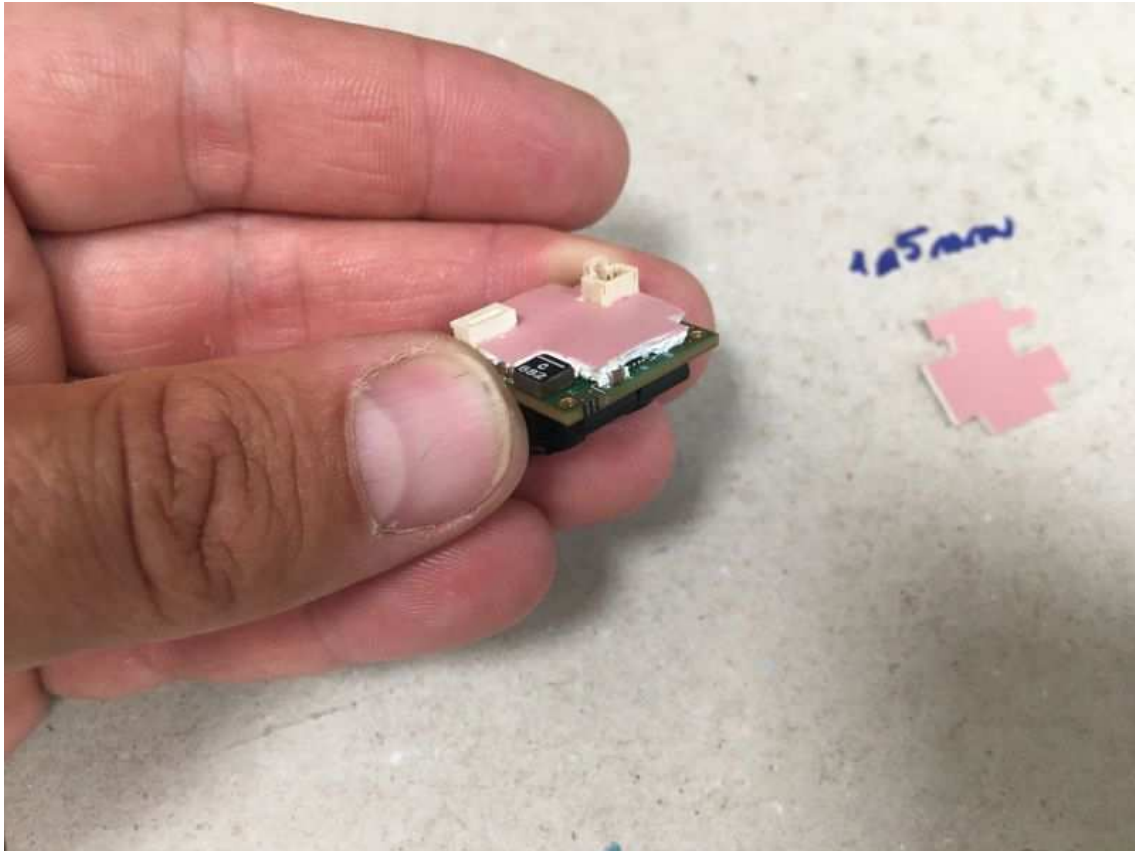


Cut-outs for 2 SMD connectors and corners' cut-outs for the heatsink body

3. Place the 2mm thermal pad cut over the PCB. Check the cut placement around 2 connectors sitting onto the PCB. Make sure there is no thermal pad material over the L1 inductor. Once the thermal pad cut position is fixed, press the cut gently as much as available so the white part of the material flows around the components sitting onto the PCB

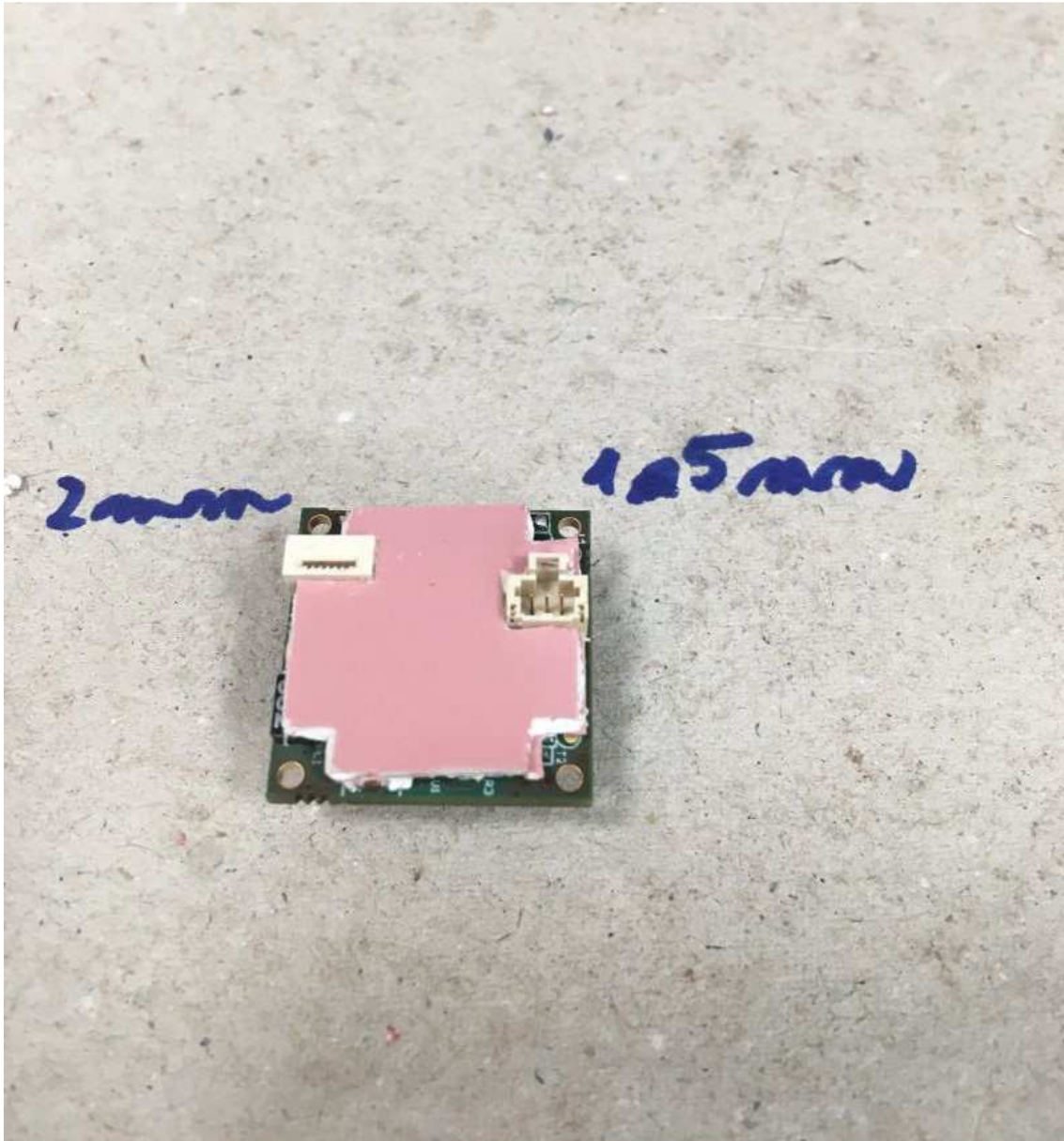


The 2mm thermal pad cut placement – check the placement and make sure no material is around the inductor. The cut should be at the same height level as the inductor after pressing.



Side-view after the 2mm thermal pad cut placement and pressing

4. Place the 1.5mm thermal pad cut over the 2mm cut. Make sure the 1.5mm cut placement follows the 2mm cut. Press the 1.5mm cut gently as much as available to create a thermal pad sandwich. No material should be present round the PCB edges – remove excessive material after pressing.

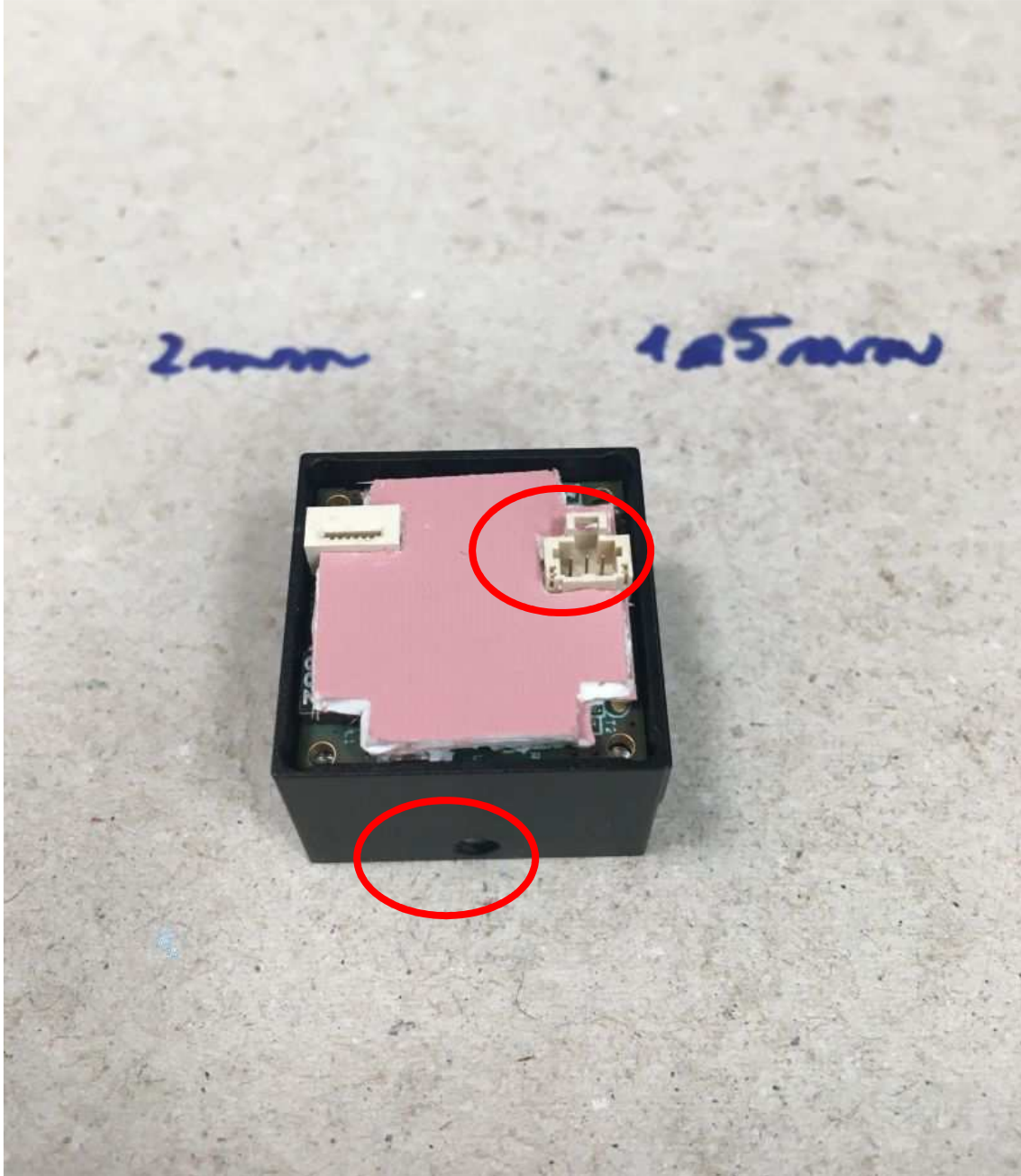


Both thermal pad cuts placement



Both thermal pad cuts placement – side view

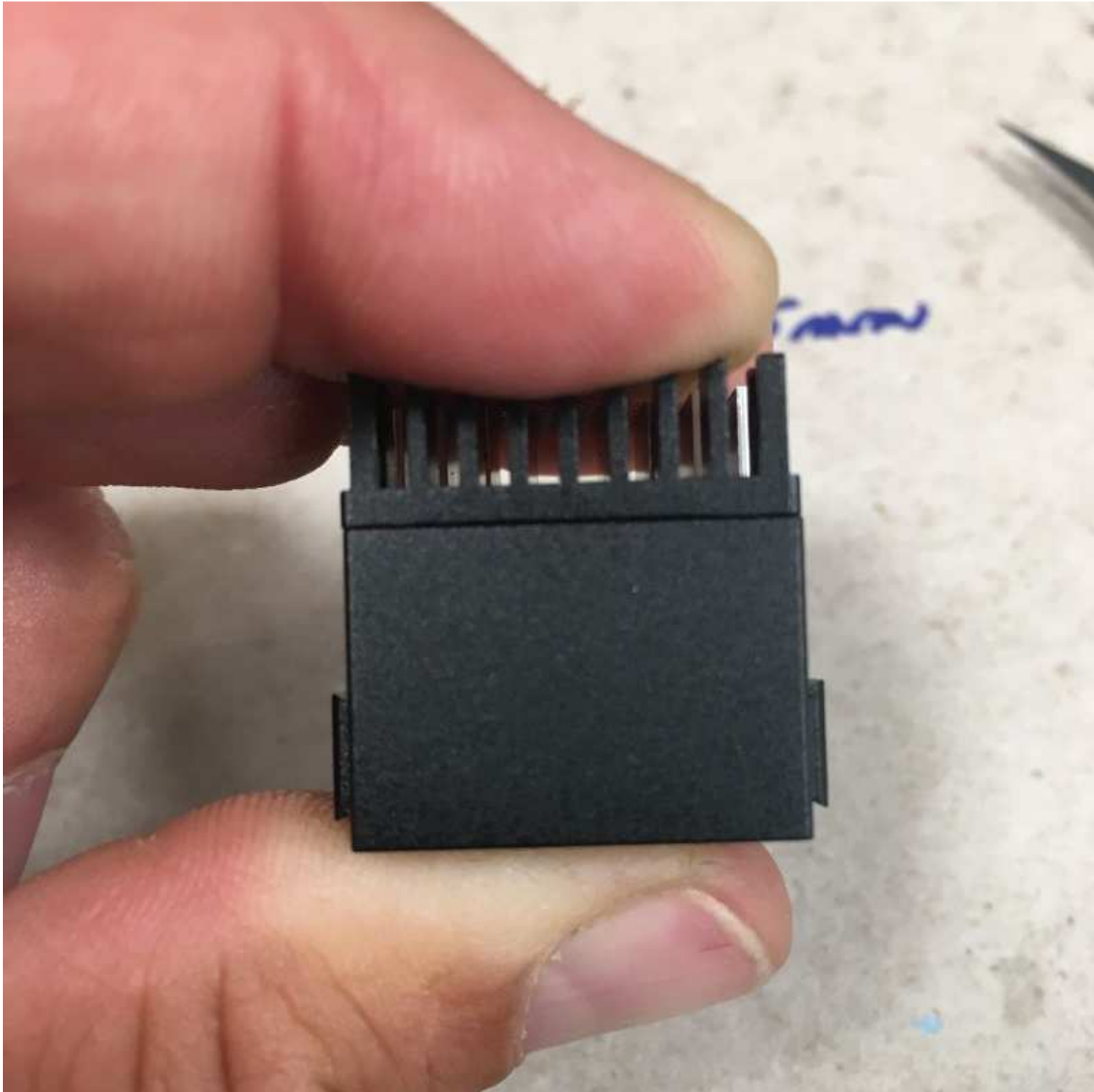
5. Place the PCB+thermal pad sandwich into the housing. The 3-pin connector is located on the right side with respect to the housing mounting hole – it is not allowed to place the PCB+thermal pad assembly rotated by 180degrees (i.e. 3-pin connector to be placed on the left side with respect to the housing hole).



PCB assembly placement with respect to the bottom part of GazeT housing

6. Place the top part of housing over the bottom part and press gently. After several press actions there should be almost no space visible between the bottom and the top part of housing. It is important there is some tension still present between both parts of the housing to ensure good thermal conduction between the PCB and the housing material.

In case there is still some space after pressing between the housing parts, remove the top part of housing and press again the thermal pad sandwich repeatedly to allow no space housing mounting.



Top part housing placement. There should be some tension between both parts of the housing after pressing. Ideally no space should be visible after pressing.

7. Place the screws at the particular positions and fix the housing.



Screws assembled – complete housing